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ABSTRACT

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Semiconductor Packages with Leadframe Grid Arrays and Components and Methods for Making the Same

A semiconductor assembly includes a leadframe with leads having offset portions exposed at an outer surface of a material package to form a grid array. An electrically conductive compound, such as solder, may be disposed or formed on the exposed lead portions to form a grid array such as a ball grid array ("BGA") or other similar array-type structure of dielectric conductive elements. The leads may have inner bond ends including a contact pad thermocompressively bonded to a bond pad of the semiconductor chip to enable electrical communication therewith and a lead section with increased flexibility to improve the thermocompressive bond. The inner bond ends may also be wirebonded to the bond pads. Components for and methods of forming semiconductor assemblies are included.

[Figure 1]